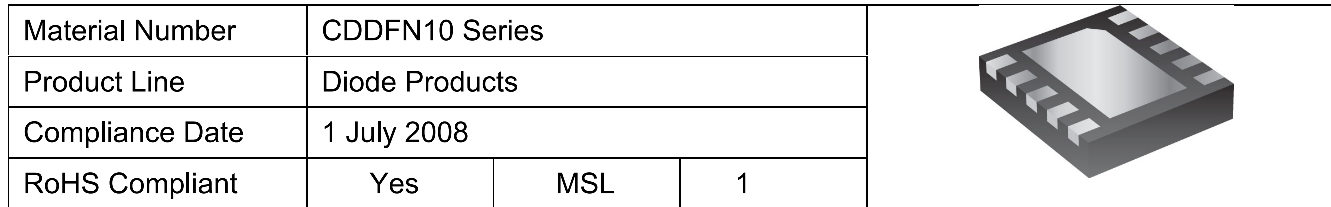
MATERIAL DECLARATION SHEET



Material Number	CDDFN10 Series		
Product Line	Diode Products		
Compliance Date	1 July 2008		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Chip	0.052	Doped Silicon	7440-21-3	100	1.707	1.707
2	Lead Frame	Base Metal	1.24	Copper	744-50-8	96.75	39.39	40.709
		Base Metal		Iron	7439-89-6	2.33	0.95	
		Base Metal		Phosphorus	7723-14-0	0.073	0.03	
		Base Metal		Zinc	7440-66-6	0.098	0.04	
		Plating		Nickel	7440-02-0	0.663	0.27	
		Plating		Palladium	744-05-3	0.039	0.0160	
		Plating		Gold	7440-57-5	0.0095	.0039	
		Impurity		Lead	7439-92-1	0.03	0.0124	
3	Bond Wire	Gold Metal	0.02	Gold	7440-57-5	68.59	0.45	0.656
4	Die Attach Adhesive	Others	0.06	Others	-	39.61	0.78	1.969
		Conductive Material		Silver	7440-22-4	59.97	1.181	
5	Mold Compound	Filler	1.68	Epoxy resin	68928-70-1	5.47	3.02	55.12
		Filler		Phenol resin	29690-82-2	3.44	1.9	
		Hardener		Silica	60676-86-0	80.169	44.189	
		Filler		Carbon Black	1333-86-4	0.238	0.131	
		Filler		Others	-	10.468	5.77	
		Total weight	3.046					

This Document was updated on: 18-march 2009

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.